

# LNJ053X8BRA3

## High Bright Surface Mounting Chip LED

SV (Side View) -0.5 Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	40	mW
Forward current	$I_F$	10	mA
Pulse forward current *	$I_{FP}$	50	mA
Reverse voltage	$V_R$	5	V
Operating ambient temperature	$T_{opr}$	-30 to +85	°C
Storage temperature	$T_{stg}$	-40 to +100	°C

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

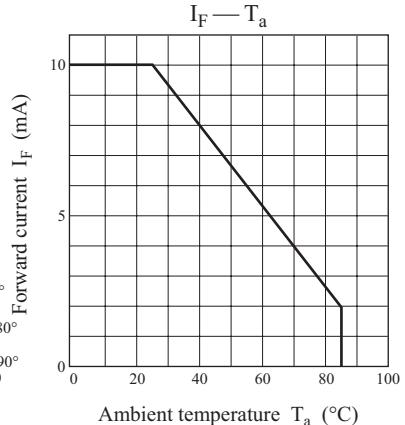
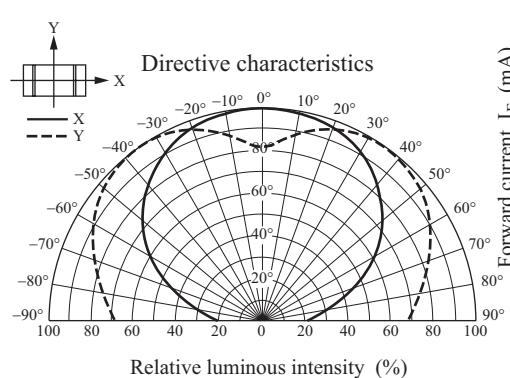
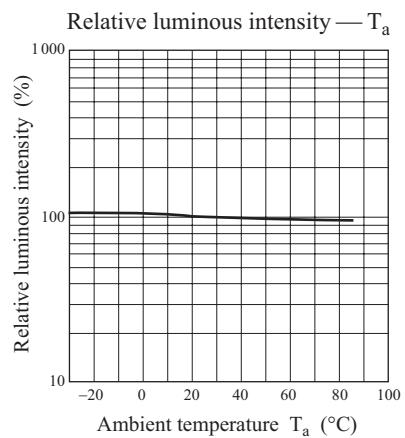
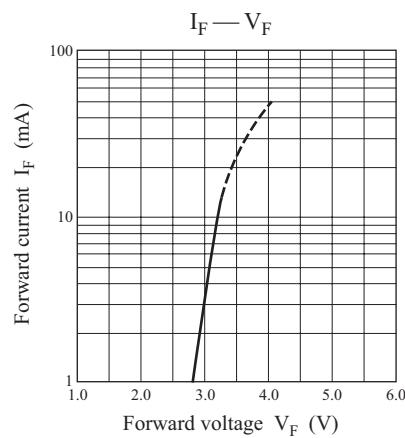
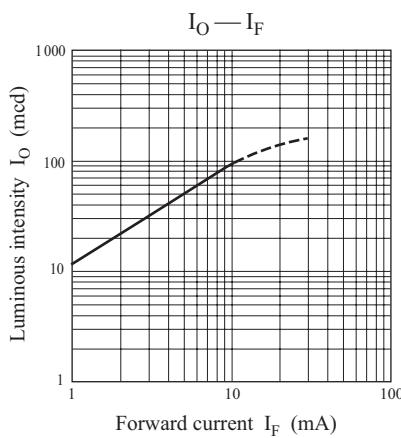
### ■ Lighting Color

- White

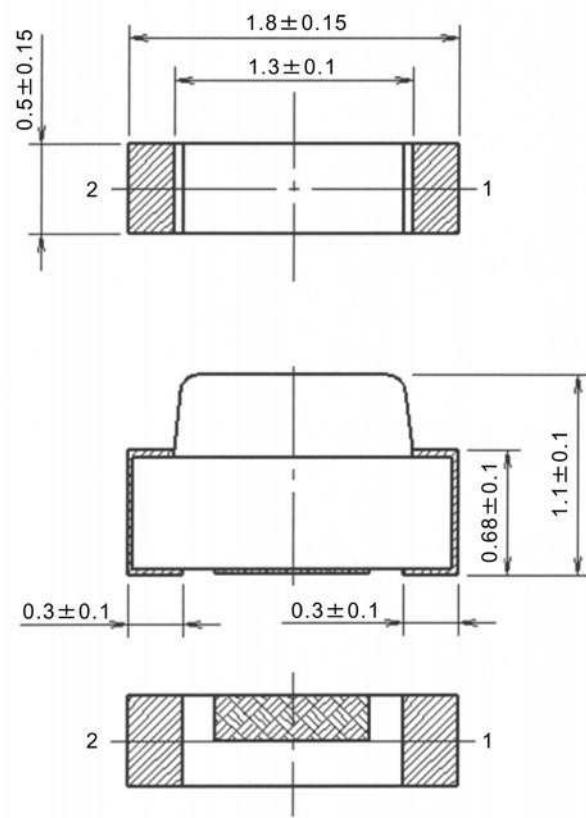
### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	$I_O$	$I_F = 5 \text{ mA}$	38	50	90	mcd
Reverse current	$I_R$	$V_R = 5 \text{ V}$			10	μA
Forward voltage	$V_F$	$I_F = 5 \text{ mA}$		3.1	3.7	V
Chromaticity coordinates	x	$I_F = 5 \text{ mA}$		0.30		—
	y	$I_F = 5 \text{ mA}$		0.30		—

Note) \*: Measurement tolerance:  $\pm 20\%$



## ■ Package (Unit: mm)



## • Pin name

1: Anode

2: Cathode

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